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MDCOG128128B6W-F2NMLW	128 x 128		LCD Module			
Specification						
Version: 1		Date: 03/01/2020				
	Re	vision				
1 09/12/2019 2 30/12/2019		ssue y Precautions in use of LCD Modu	les			

Display F	Display Features					
Resolution	128 x 128					
Appearance	Black on White					
Logic Voltage	3V		1			
Interface	I ² C / Parallel / SPI		, HC			
Font Set			OHS			
Display Mode	Transmissive	CC	mpliant			
LC Type	FSTN					
Module Size	55.00 x 57.00 x 6.18mm					
Operating Temperature	-20°C ~ +70°C					
Construction	COG	Box Quantity	Weight / Display			
LED Backlight	White					

* - For full design functionality, please use this specification in conjunction with the ST75161 specification. (Provided Separately)

Display Accessories						
Part Number	Description					
MCIB-12	UNO 32 Breakout Board with SD Card and LED BKL driver.					
MPBV-7	30-Way FFC to Cable and Wires 0.5mm Pitch.					

Optional Variants					
Appearances	Voltage				
White on Blue					
Black on Yellow/Green					
Black on RGB					

General Specification

The Features of the Module is description as follow:

■ Number of dots: 128 x 128

■ Module dimension: 55.0 x 57.0 x 6.18 mm

■ View area: 42.0 x 42.0 mm

Active area: 44.0 x 44.0 mm

■ Dot size: 0.308 x 0.308 mm

■ Dot pitch: 0.310 x 0.310 mm

■ LCD type: FSTN Negative (Double film) Transmissive

■ Duty: 1/136 DUTY,1/12 BIAS

■ View direction: 6 o'clock

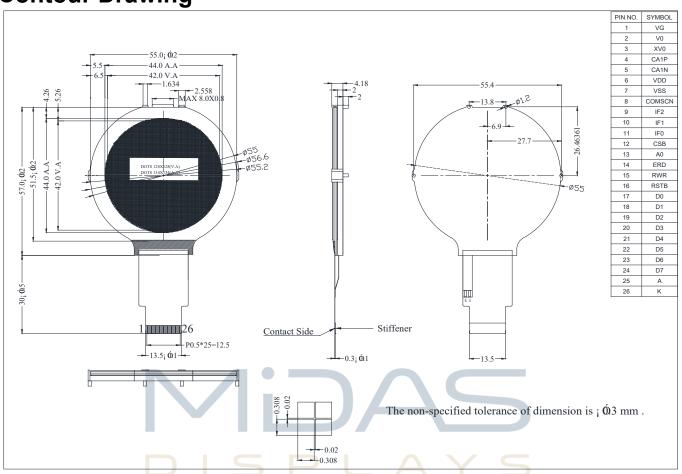
■ Backlight Type: LED White MANUFACTURE • SUPPLY

■ IC: ST75161

Interface Pin Function

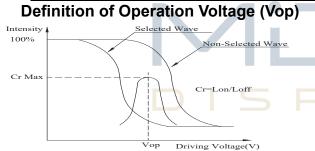
Pin No.	SYMBOL	Function
1	VG	VG is the power of SEG-drivers.
2	V0	Positive operating voltage of COM-drivers.
3	XV0	Negative operating voltage of COM-drivers.
4	CA1P	DC/DC voltage converter
5	CA1N	DC/DC Vollage Converter
6	VDD	Power supply
7	VSS	Ground
8	COMSCN	Set scan direction of COM.
9	IF2	
10	IF1	These pins select interface operation mode.
11	IF0	
12	CSB	Chip select input pin.
13	A0	It determines whether the access is related to data or command.
14	ERD	Read / Write execution control pin.
15	RWR	Read / Write execution control pin.
16	RSTB	Hardware reset input pin
17-24	DO-D7	When using 8-bit parallel interface: 8080 or 6800 mode:8 bit bi-directional data bus When using serial interface: 4-line SPI or 3-line SPI mode D[7:4]: fix to "H" by VDD1. D[3:1]: serial input/output data (SDA). D[0]: serial input clock (SCL). D1 to D3 must be connected together (SDA) When using serial interface: I2C interface D[7]: SA[1], I2C slave address bit. Must be connected to VDD1 or VSS1. D[6]: SA[0], I2C slave address bit. Must be connected to VDD1 or VSS1. D[5:4]: fix to "H" by VDD1. D[3:2]: SDA_OUT, serial data and acknowledge output for the I2C interface. D[1]: SDA_IN, serial input data D[0]: SCL, serial input clock. D1 to D3 must be connected together (SDA) CSB must be fixed to "L" by VSS1.
25	А	Anode input for LED backlight.
26	К	Cathode input for LED backlight

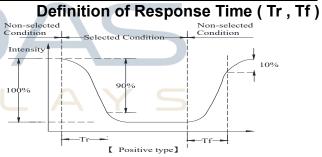
Contour Drawing

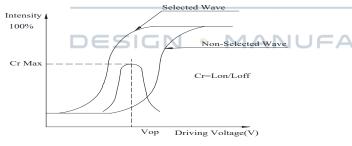


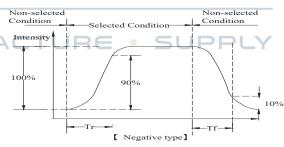
Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	25	30	_	ψ= 180°
View Arele	θ	CR≧2	35	40	_	ψ= 0°
View Angle	θ	CR≧2	40	45	_	ψ= 90°
	θ	CR≧2	40	45	_	ψ= 270°
Contrast Ratio	CR	_	20	40	_	_
_	T rise	_	_	150	225	ms
Response Time	T fall	_	_	220	330	ms





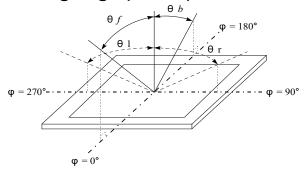




Conditions:

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)



Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	${\mathbb C}$
Storage Temperature	Тѕт	-30	_	+80	${\mathbb C}$
Power Supply Voltage	VDD	-0.3	_	4.0	V
LCD Power supply voltage	VLCD	-0.3	_	20	V
LCD Power supply voltage	V0-XV0	-0.3	_	19	V
Input voltage	VIN	-0.3		VDD+0.3	V

Electrical Characteristics

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	V _{DD} -V _{SS}	_	2.7	3.0	3.3	- V
DESIGN •	MANU	Ta=-20°€	IR€ •	SUF	PPLY	V
Supply Voltage For LCD	Vop	Ta=25℃	13.7	14.0	14.3	V
		Ta=70℃	_	_	_	V
Input High Volt.	ViH	_	0.7 V _{DD}	_	V_{DD}	V
Input Low Volt.	VıL	_	Vss	_	0.3 V _{DD}	V
Output High Volt.	V _{OH}	_	0.8 V _{DD}	_	V_{DD}	V
Output Low Volt.	V_{OL}	_	Vss	_	0.2 V _{DD}	V
Supply Current	I_{DD}	V _{DD} =3.0V	_	_	2.0	mA

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

Backlight Information

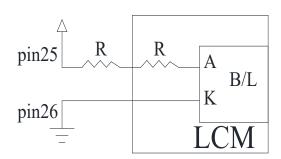
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	36	48	60	mA	V=3.5V
Supply Voltage	V	_	3.5	_	V	_
Reverse Voltage	VR	_	_	5	V	_
Chromaticity	Х	0.25	0.27	0.30	_	_
Coordinates	Υ	0.25	0.27	0.30	_	_
Luminance	11/	900	4000		a al /1002	V-2 5V
(Without LCD)	IV	800	1000		ca/m-	V=3.5V
LED Life Time				JA	\rightarrow	ILED=48mA
(For Reference	_		50K	_	Hr.	25℃,50-60%RH,
only)					A	(Note 1)
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

Drive from pin25,pin26



Reliability

Content of Reliability Test (Wide temperature, -20℃~70℃)

Environmental Test						
Test Item	Content of Test	Test Condition	Not e			
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 96hrs	2			
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 96hrs	1,2			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 96hrs	_			
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 96hrs	1			
High Temperature/ Humidity storage	The module should be allowed to stand at 40 °C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	40℃,90%RH 96hrs	1,2			
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20 ℃ 25 ℃ 70 ℃ 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles				
DESIGN Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact)				

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				
02	Black or white spots on LCD (display only)	2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.2.2 Densely spaced: No more than two spots or lines within 3mm				2.5
03	LCD black spots, white spots, contamination	3.1 Round type : Φ=(x+y)/2		SIZE Φ≦0.10 0.10<Φ≦0.20 0.20<Φ≦0.25 0.25<Φ	Acceptable Q TY Accept no dense 2 1 0	2.5
	(non-display)	3.2 Line type : (A	Length L≦3.0 L≦2.5	g drawing) Width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≦0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5

04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5
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NO	Item	Criterion					
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination					
		Symbols Define: x: Chip length k: Seal width t: Chip length t: Chip length 6.1 General glass chip is chi	spots, white spots, concentration of the content of	x: Chip length x: Chip length x≤ 1/8a x≤ 1/8a y SUPPLY	2.5		
		z: Chip thickness	y: Chip width	x: Chip length			
		Z≦1/2t	Not over viewing area	x≦1/8a			
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a			
		⊙If there are 2 or more	chips, x is the total leng	yth of each chip.			

NO	Item	Criterion						
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:						
		y: Chip width x: Chip length z: Chip thickness						
		y≦0.5mm	x≦1/8a	$0 < z \le t$				
	6.2.2 Non-conductive portion:							
06	Glass crack	y X	L V	1 Z	2.5			
		v: Chin width	x: Chin length	z: Chip thickness				
	Des		x: Chip length x≦1/8a	$0 < z \le t$				
		y≦ L						
		inal, over 2/3 of the ITO						
			e inspected according	to electrode terminal				
		specifications.						
		⊙If the product will be heat sealed by the customer, the alignment mark not be damaged.						
		6.2.3 Substrate protuberance and internal crack.						
	x							
	x: length							
	$y \le 1/3L$ $x \le a$							
		Yan						

NO	Item	Criterion		
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5	
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65	
		 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 	2.5 2.5 0.65	
	PCB · COB	10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.10.5 No oxidation or contamination PCB terminals.	2.5	
10		 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product 	0.65	
		characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB	2.5	
		X * Y<=2mm2	2.5	
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.11.2 No cold solder joints, missing solder connections, oxidation or icicle.	2.5	
		11.3 No residue or solder balls on PCB.11.4 No short circuits in components on PCB.	2.5 0.65	

NO	Item	Criterion			
NO 12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet.	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65		
12	appearance	12.7 Sealant on top of the ITO circuit has not hardened.			
			0.65		
		12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on	0.65		
		packaging specification sheet. 12.11 Product dimension and structure must conform to product	0.65		
		specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection.			

Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Midas Displays have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Midas Displays have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Midas Displays have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

DESIGN • MANUFACTURE • SUPPLY

Material List of Components for RoHs

1. Midas Displays hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	Cd	Pb	Hg	Cr6+	PBB	PBDE	DEHP	BBP	DBP	DIBP
Limited	100	1000	1000	1000	1000	1000	1000	1000	1000	1000
Value	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm	ppm
Above limited value is set up according to RoHS.										

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp.:

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.

